

**SMD INFRARED EMITTING DIODES**
**BL-LS1311IR**
**Features:**

- 3.5mmx2.8mm SMD, 1.9mm THICKNESS PLCC2 package, Infrared LED
- High Reliability
- Peak Wavelength at 940, 880, 850nm
- Water Clear, yellow Transparent, Blue Transparent available
- IC compatible /Low current capability.
- PACKAGE: 2KPCS/REEL.
- RoHs Compliance


**Applications:**

- Free air transmission system
- Infrared remote control units with high power requirement
- Smoke detector
- Infrared Camera
- Infrared applied system

**Electrical-optical characteristics: (Ta=25°C) (Test Condition: IF=50mA)**

Part Number	Chip		Lens Type	$\Delta\lambda$	Ir (Vr=5V, uA)	Forward Voltage(VF) Unit:V		Radiant Power (mw/sr) Typ	Viewing Angle 2θ1/2(deg )
	Material	$\lambda_p$ (nm)				Typ	Max		
<b>BL-LS1311IRAC</b>	GaAs	940	Water Clear	50	10	1.40	1.60	30	120
<b>BL-LS1311IRAB</b>	GaAs	940	Blue Trans.	50	10	1.40	1.60	30	
<b>BL-LS1311IRBC</b>	GaAlAs	880	Water Clear	50	10	1.70	2.00	30	
<b>BL-LS1311IRBB</b>	GaAlAs	880	Blue Trans.	50	10	1.70	2.00	30	
<b>BL-LS1311IRCC</b>	GaAlAs	850	Water Clear	50	10	1.70	2.00	50	
<b>BL-LS1311IRCB</b>	GaAlAs	850	Blue Trans.	50	10	1.70	2.00	50	
<b>BL-LS1311IRCY</b>	GaAlAs	850	Yellow Trans.	50	10	1.70	2.00	50	

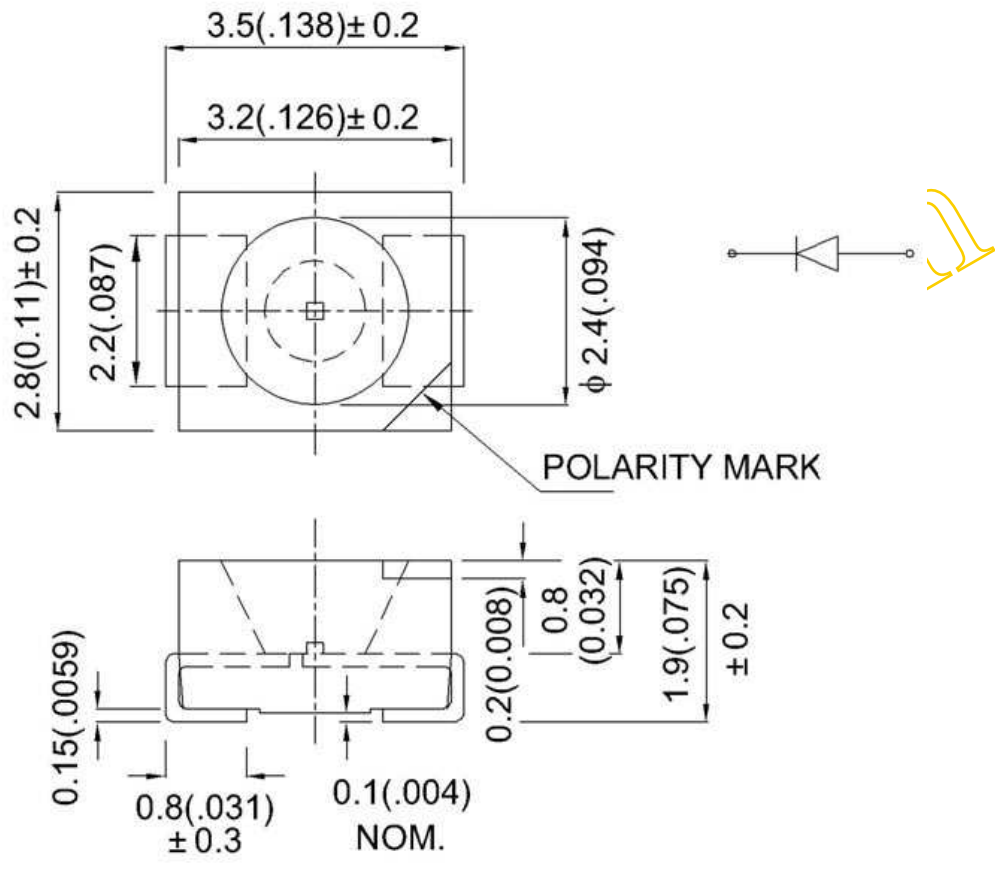
**Absolute maximum ratings (Ta=25°C)**

Parameter	Rating	Unit
Forward Current $I_F$	50	mA
Power Dissipation $P_d$	160	mW
Reverse Voltage $V_R$	5	v
Peak Forward Current $I_{PF}$ (Duty 1/10 @1KHZ)	250	mA
Operation Temperature $T_{OPR}$	-40 to +100	°C
Storage Temperature $T_{STG}$	-40 to +100	°C
Lead Soldering Temperature $T_{SOL}$	Max.260±5°C for 3 sec Max. (1.6mm from the base of the epoxy bulb)	°C

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■ **Package configuration & Internal circuit diagram**



Notes:

1. All dimensions are in millimeters (inches)
2. Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
3. Specifications are subject to change without notice.

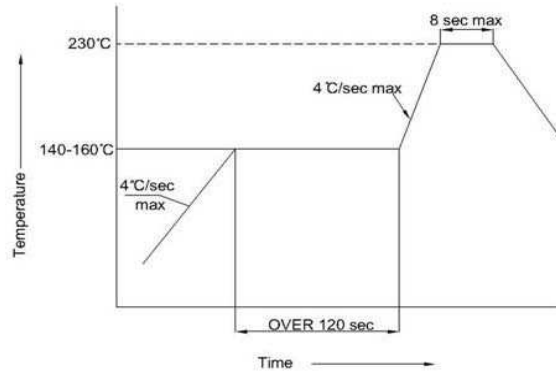
## SMD INFRARED EMITTING DIODES

BL-LS1311IR

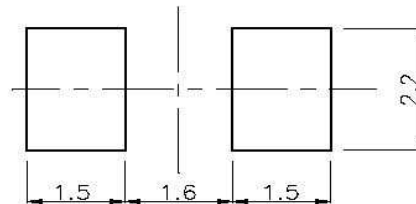
### ■ Tape Specifications

#### SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process:



Recommended Soldering Pattern  
(Units : mm)



Tape Specifications  
(Units : mm)

